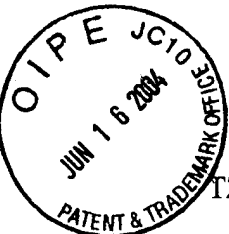


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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

TZ-CHENG CHIU

Serial No. 10/631,130 (TI-35061)

Filed July 31, 2003

For: COMPOSITE LID FOR LAND GRIP ARRAY
(LGA) FLIP CHIP PACKAGE ASSEMBLY

Art Unit 2825

Examiner Calvin Lee

Customer No. 23494

Mail Stop Issue Fee
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

<p>CERTIFICATE OF MAILING OR TRANSMISSION UNDER 37 CFR 1.8</p> <p>I hereby certify that the attached document is being deposited with the United States Postal Service with sufficient postage for First Class Mail in an envelope addressed to Director of the United States Patent and Trademark Office, P.O. Box 1450,, Alexandria, VA 22313-1450 or is being facsimile transmitted on the date indicated below:</p> <p>6-18-04</p> <p><i>[Signature]</i></p> <p>Jay M. Cantor, Reg. No. 19,906</p>

COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

Sir:

In response to the reasons for allowance set forth in the Notice of Allowability, while applicant agrees with the stated reasons for allowance as a basis for allowance of claims 1 to 10 of the subject application, it should be noted that the examiner stated that the reason provided was "a" reason and not the sole reason.

Claim 2 additionally requires that the first material comprise a portion of the lid adjacent to the die, and the second material comprise a perimeter of the lid, this feature being patentable in itself.

Claim 3 additionally requires that the first material comprise a portion of the lid adjacent to the die, and the second material be situated in a corner of the lid, this feature being patentable in itself.

Claim 4 additionally requires that the modulus of elasticity of the second material be at least twice the modulus of elasticity of the first material, this feature being patentable in itself.

Claim 5 additionally requires that the first material have a thermal conductivity of at least about 250 W/mK, this feature being patentable in itself.

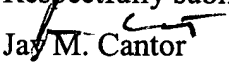
Claim 6 additionally requires that the second material have a coefficient of thermal expansion of between about 4 ppm/°C and about 8 ppm/°C, this feature being patentable in itself.

Claim 7 additionally requires that the first material be a material selected from a group consisting of copper and aluminum, this feature being patentable in itself.

Claim 8 additionally requires that the second material be a material selected from a group consisting of copper-tungsten (Cu-87%W), tungsten, and silicon carbide, this feature being patentable in itself.

Claim 9 additionally requires a die attached to the first material by a low-modulus thermal compound, this feature being patentable in itself.

Claim 10 additionally requires that the thermal compound have a modulus of elasticity of less than 0.03 GPa, this feature being patentable in itself.

Respectfully submitted,

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